

Abstract

5 A small package is provided for a flash EEPROM memory. The small
package uses terminals which are part of a bottom conductive layer of a circuit
board. In this manner, the final package can be quite thin. The circuit board can
be connected to the integrated circuits and passive devices and can be encapsulated
in plastic or glued to a plastic cover. In this manner, a thin and relatively
inexpensive package can be formed. Additionally, the circuit board can have
10 testing connections which can be removed before forming the final package.

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